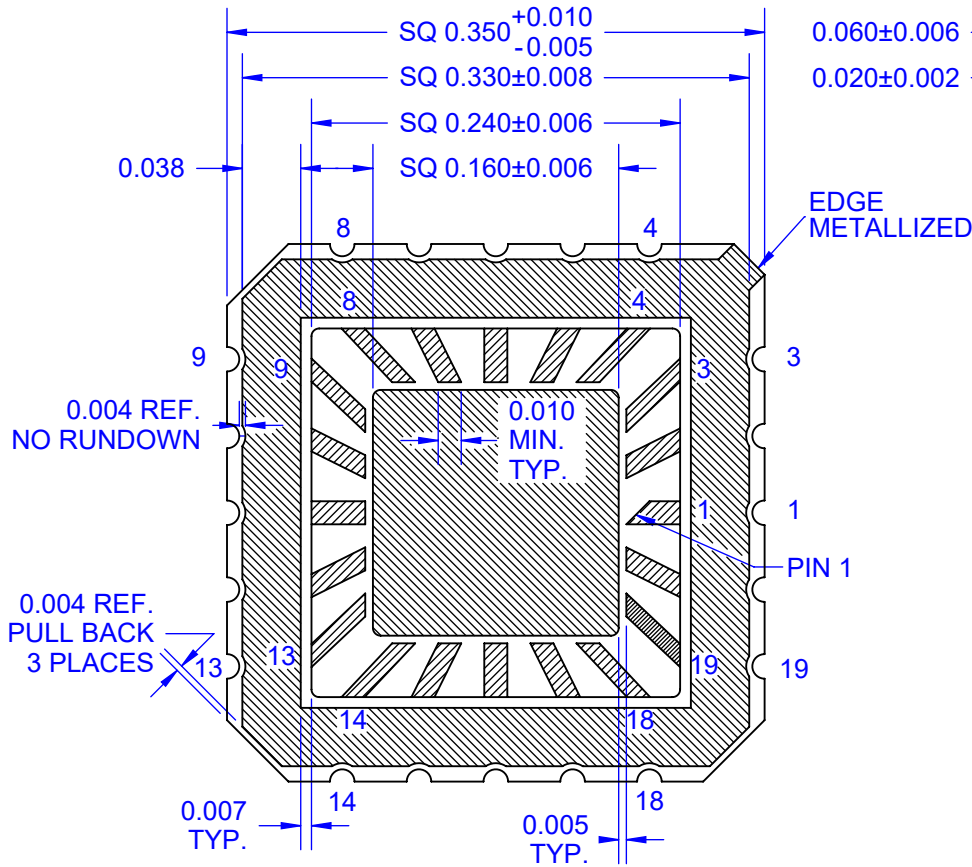
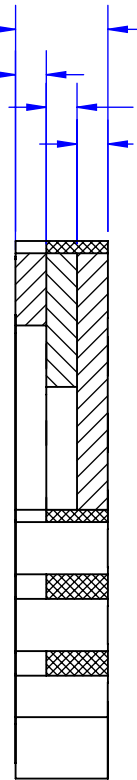


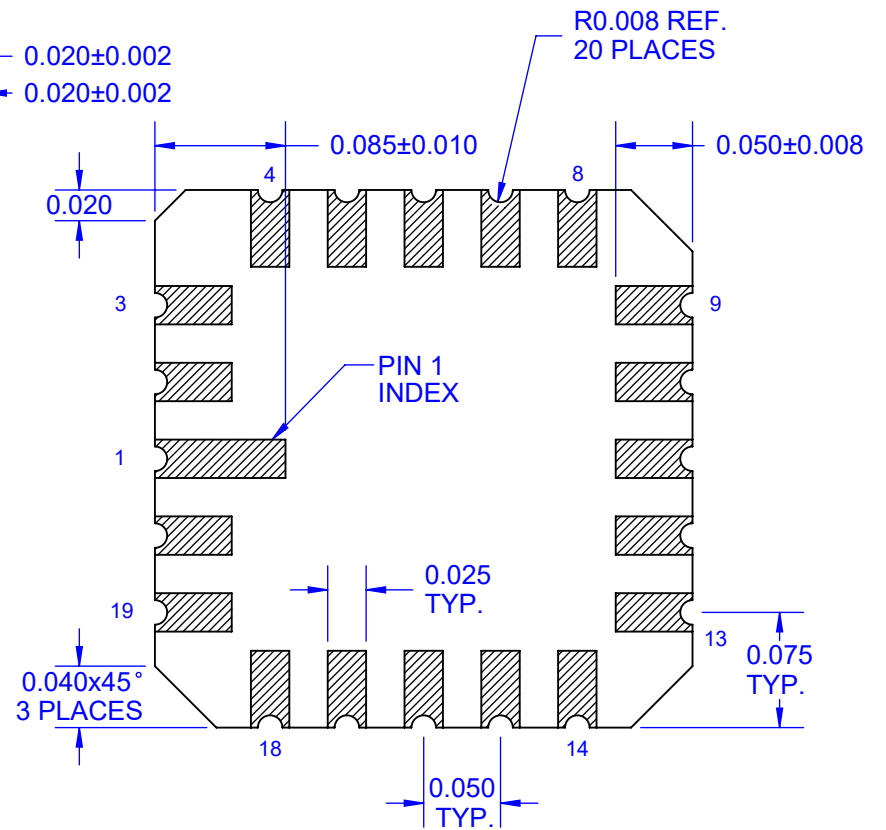
TOP VIEW



SIDE VIEW



BOTTOM VIEW



DIE PAD
0.160 x 0.160-inch
[4.06 x 4.06mm]

NOTES: (Unless Otherwise Specified).

1) DIMENSION in INCH.

2) PLATING:

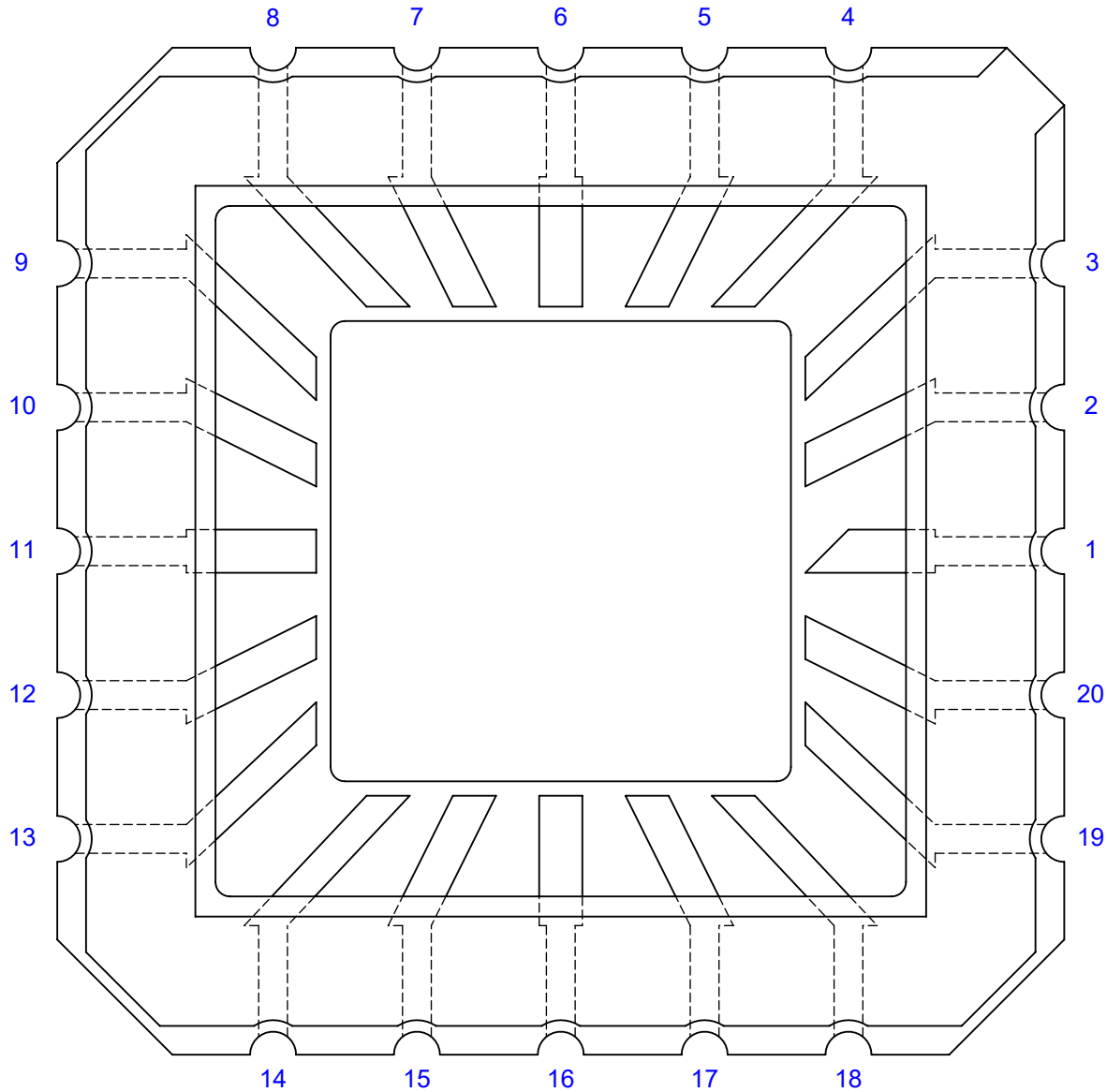
Ni 80 Micro-inch (2.0um) MIN.

Au 60 Micro-inch (1.5um) MIN.

3) SEAL RING AND DIE ATTACH SHALL BE ISOLATED FROM ALL LEADS.

APPROVALS	DATE	TopLine®			
DRAWN T. Au	05/14/16				
ENG M. Hart	05/14/16	TITLE LCC20B50SQ.35-N160			
MFG		SCALE 10:1	SIZE A	DRAWING NO. 192220	REV A
QA					
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 4
REVISED					

BOND PAD DIAGRAM



TopLine[®]

TITLE LCC20B50SQ.35-N160

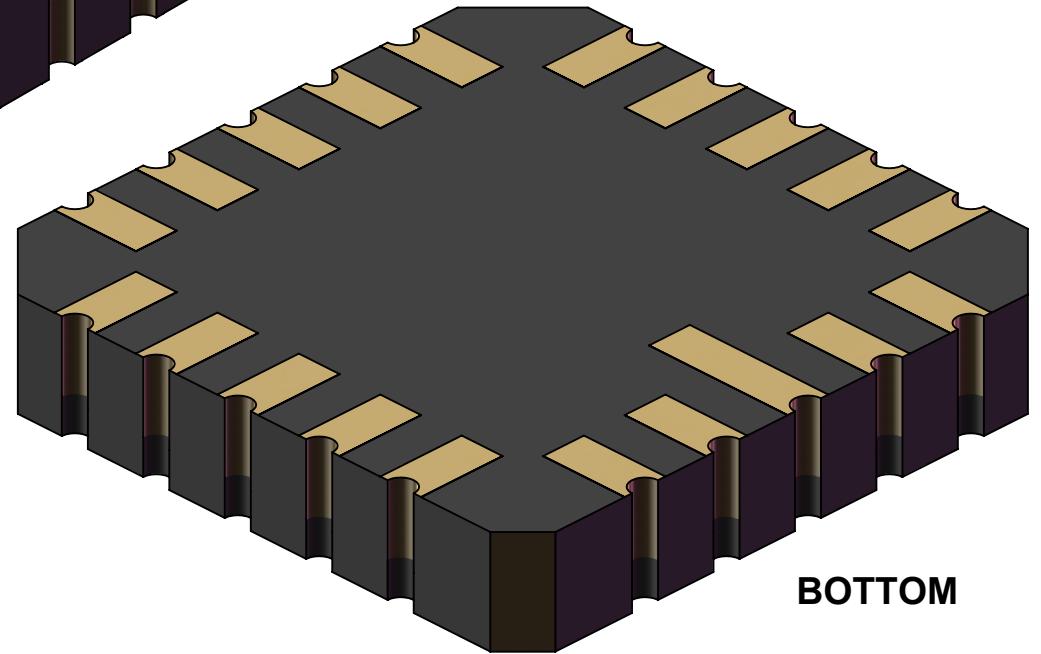
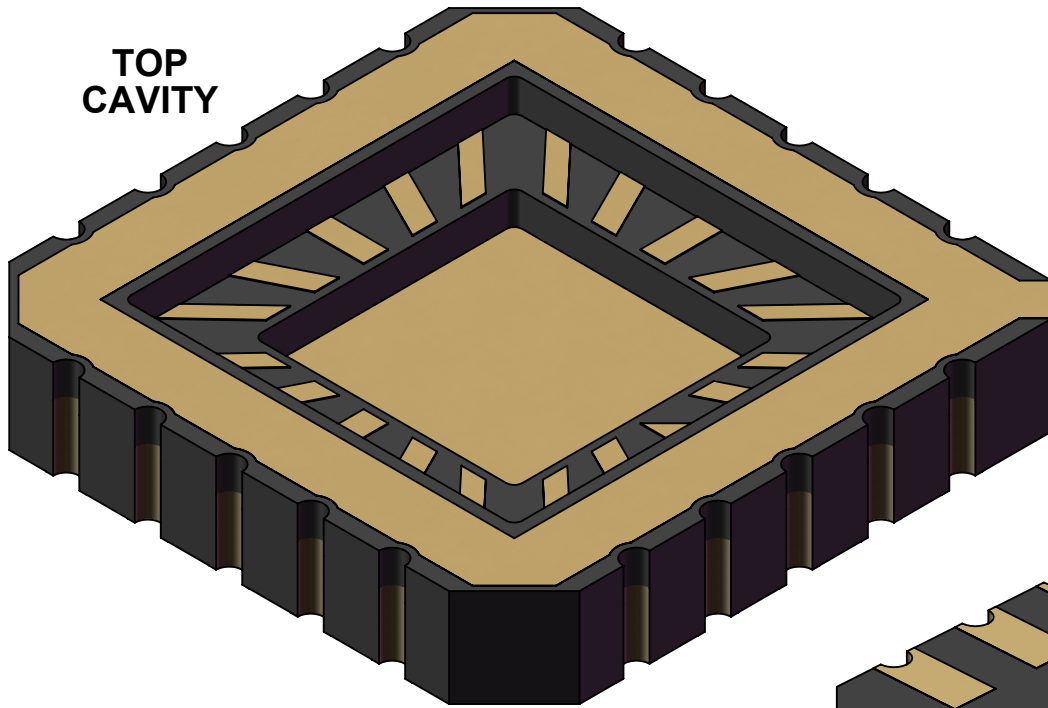
SCALE 16:1	SIZE A	DRAWING NO. 192220	REV A
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DO NOT SCALE DRAWING

SHEET 2 OF 4

MODEL

TOP
CAVITY



BOTTOM

TopLine[®]

TITLE LCC20B50SQ.35-N160

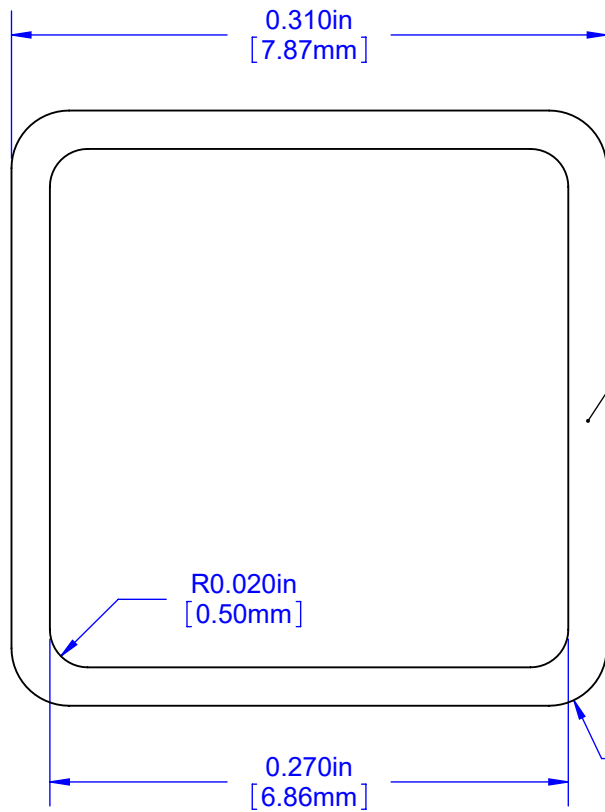
SCALE 12:1	SIZE A	DRAWING NO. 192220	REV A
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DO NOT SCALE DRAWING

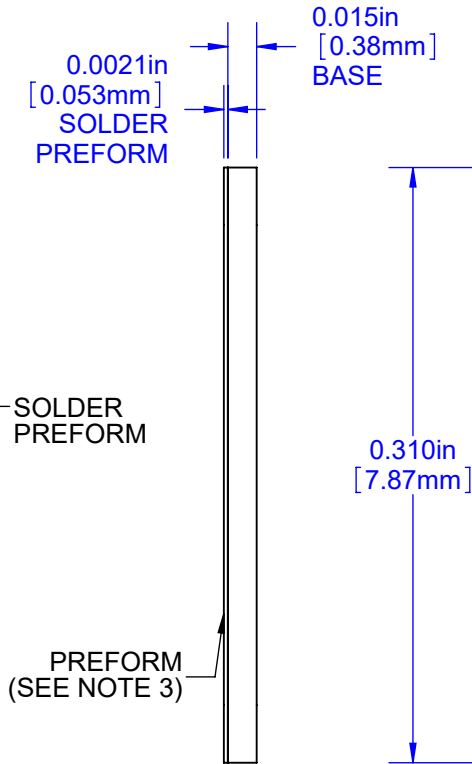
SHEET 3 OF 4

COMBO LID

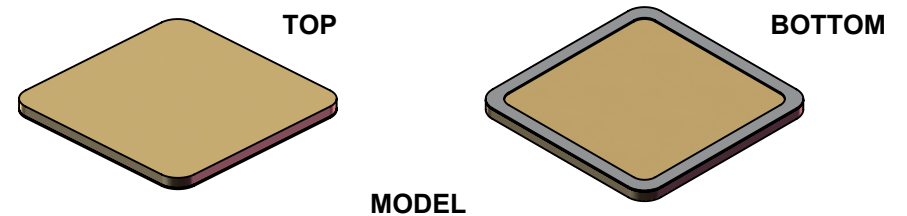
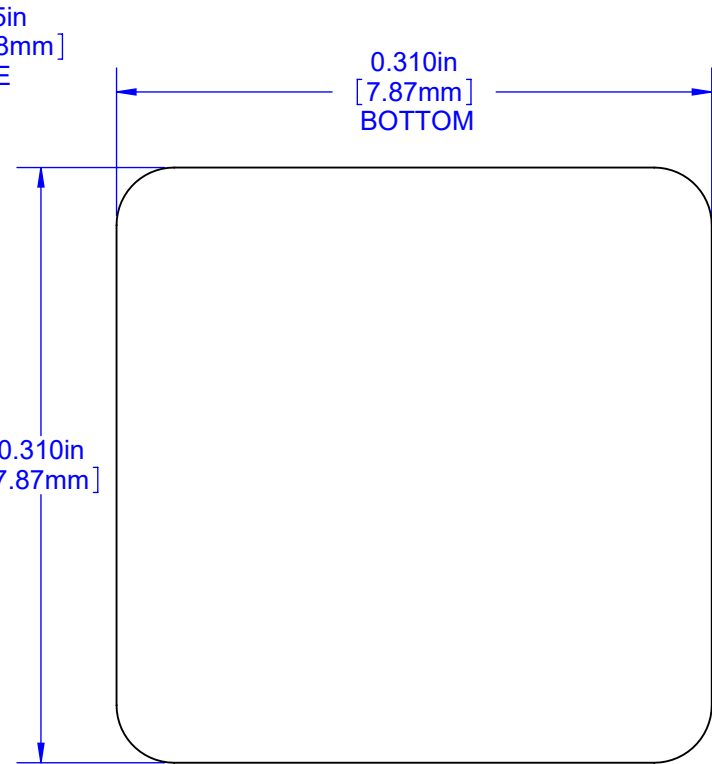
BOTTOM



SIDE



TOP



NOTES:

1. BASE MATERIAL: KOVAR or ALLOY 42.
2. PLATING: Ni 50~350 MICRO-INCH PER SIDE.
Au 25 MICRO-INCH MIN PER SIDE.
3. SOLDER PREFORM: Au 80% ±1.0 Sn 20%.
4. FLATNESS 1.0 MIL (25µm) MAXIMUM PER 0.5-inch (12.7mm).

TopLine®			
TITLE		CL-310SQ-A COMBO LID	
SCALE	SIZE	DRAWING NO.	REV
10:1	A	163851	A
DO NOT SCALE DRAWING			SHEET 4 OF 4